PATENT ASSIGNMENT

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SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TPACK	02/14/2011

RECEIVING PARTY DATA

Name:	Applied Micro Circuits Corporation
Street Address:	9868 Scranton Road, Suite 1200
City:	San Diego
State/Country:	CALIFORNIA
Postal Code:	92121

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12145466

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: TPACK-00003

NAME OF SUBMITTER: Gerald Maliszewski

Total Attachments: 2

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PATENT REEL: 025812 FRAME: 0828

Corporate to Corporate Assignment

WHEREAS, TPACK A/S, (hereinafter termed "TPACK"), a corporation of the Country of Denmark, having an address at Hoerkaer 12A, 2730 Herlev, Denmark, is, by one or more assignment documents recorded in the United States Patent and Trademark Office, the present assignee and record owner of an interest the following United States Letters Patents and Pending Applications (hereinafter termed "said applications");

Abandoned Patent Application:	Serial No. US 10/791,374	TPACK-001
Pending Application:	Serial No. US 11/253,527	TPACK-001 CON1
Patent		
PCT (granted):	Serial No. PCT/DK02/00573	TPACK-001 PCT
EP (granted):	Serial No. EP1436945	TRACK-001 EP
Austria (abandoned):	Serial No. AT20020797564	TPACK-001 EP/AT
Germany (granted):	Serial No. DE20026027970	TPACK-001 EP/DE
France (granted):	Serial No. EP20020797564	TPACK-001 EP/FR
GB (granted):	Serial No. EP20020797564	TPACK-001 EP/GB
Patent HK: HK1067259	Serial No. HK20050100282	TPACK-001 CON1 HK
Patent US 7,499,449	Serial No. US 11/122,981	TPACK-002
Patent		
PCT (granted):	Serial No. PCT/DK03/00762	TPACK-002 PCT
EP (pending):	Serial No. EP20030810379	TPACK-002 EP
AU (abandoned):	Serial No. AU2003275951	TPACK-002 PCT/AU
CA (abandoned):	Serial No. CA20032505245	TPACK-002 PCT/CA
CN (granted):	Serial No. CN200380107841	TPACK-002 PCT/CN
IN: (granted) IN241562	Serial No.1153/CHENP/2005	TPACK-002 PCT/IN
JP: (granted) JP4451389	Serial No. JP20050502098	TPACK-002 PCT/JP
KR (abandoned):	Serial No. KR20057008159	TPACK-002 PCT/KR
Pending Application:	Serial No. 12/358,252	TPACK-002 CON1
Pending Application:	Serial No. 12/145,466	TPACK-003
Pending Application:	Serial No. PCT/US08/68812	TPACK-003 PCT
Pending Application:	Serial No. EP08874790	TPACK-003 EP
Pending Application:	Serial No. 12/124,225	TPACK-004
Pending Application:	Serial No. PCT/IB08/03697	TPACK-004
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and in the inventions to which said applications pertain (hereinafter termed "said inventions"); and

WHEREAS, APPLIED MICRO CIRCUITS CORPORATION, INC. (hereinafter named "AMCC"), a corporation of the State of Delaware, having an address at 9868 Scranton Road, Suite 1200, San Diego, CA, is the true and equitable owner of all patents which ultimately issue from patent applications filed by TPACK under the terms of a mutual agreement between TPACK and AMCC (hereinafter termed the "Basic Agreement"); and

WHEREAS, TPACK and AMCC mutually acknowledge and agree that the terms of said Basic Agreement are applicable to said applications and said inventions and that, by operation of said Basic Agreement, AMCC is, upon issuance of said applications, the true and equitable owner of any and all rights which TPACK may possess in and to said applications and said

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inventions and, furthermore, that AMCC is entitled to formal assignment of all TPACK's rights therein to AMCC, including recordation of such assignment in the records of the United States Patent and Trademark Office.

NOW, THEREFORE, for good and valuable consideration acknowledged by TPACK to have been received in full from AMCC, TPACK does hereby sell, assign, transfer, convey, and quitclaim unto AMCC all of TPACK's right, title and interest in and to said applications and said inventions.

The terms and covenants of this Assignment shall inure to the benefit of AMCC, its successors, assigns and other legal representatives, and shall be binding upon TPACK, its successors, assigns and other legal representatives.

The undersigned is authorized to act on behalf of the assignee in accordance with 37 CFR §3.73(b)(2)(i).

Date

Robert Gargus

Chairman of the Board of Directors

TPACK S/A

Date

Colin Macnab

President for TPACK A/S